PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT3595115

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YING DUAN	10/14/2015
CHULKYU LEE	10/14/2015
SHIH-WEI CHOU	10/27/2015
HARRY DANG	10/14/2015
OHJOON KWON	10/14/2015

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14842644	

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: qualcomm-pto@lozaip.com

LOZA & LOZA LLP **Correspondent Name:**

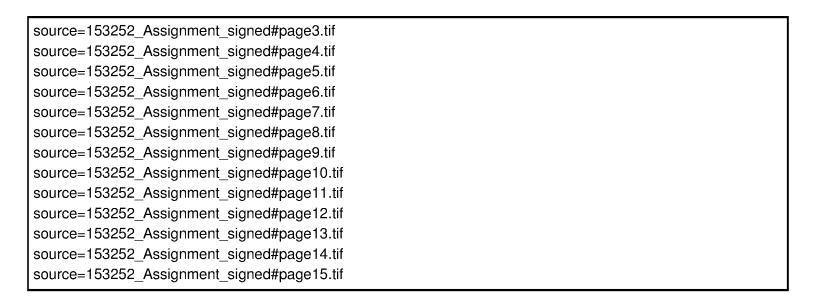
Address Line 1: 305 NORTH SECOND AVENUE #127

Address Line 4: **UPLAND, CALIFORNIA 91786**

ATTORNEY DOCKET NUMBER:	QCOM-2880US (153252)
NAME OF SUBMITTER:	JULIO LOZA
SIGNATURE:	/Julio Loza/
DATE SIGNED:	10/30/2015

Total Attachments: 15

source=153252_Assignment_signed#page1.tif source=153252_Assignment_signed#page2.tif



WHEREAS, WE,

- 1. Ying Duan, a citizen of China, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121-1714 and a resident of San Diego, California,
- 2. **Chulkyu Lee,** a citizen of Korea, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121-1714 and a resident of San Diego, California,
- 3. Shih-Wei Chou, a citizen of Taiwan, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121-1714 and a resident of San Diego, California,
- 4. Harry Dang, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121-1714 and a resident of San Diego, California,
- 5. **Ohjoon Kwon**, a citizen of Korea, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121-1714 and a resident of Irvine, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to MULTIPHASE CLOCK DATA RECOVERY FOR A 3-PHASE INTERFACE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 14/842,644 filed September 1, 2015, Qualcomm Reference No. 153252, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

Done at _	San Diego LOCATION	_, on	Ying Duan
Done at _	LOCATION	_, on	Chulkyu Lee
Done at _	LOCATION	on	Shih-Wei Chou
Done at _	LOCATION	_, on	Shih-Wei Chou
Done at _	LOCATION	_, on	Ohjoon Kwon

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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

Done at		, on	****	
	LOCATION		DATE	Ying Duan
Done at _	San Dieg LOCATION	, on _	10/14/15	4016
	LOCATION		DATE	Chulkyu Lee
TO.				
Done at_	7.001.007	, on _	DATE	
	LOCATION		DATE	Shih-Wei Chou
Done at	LOCATION	, on		
_	LOCATION	→′ −	DATE	Shih-Wei Chou
Done at		, on		
	LOCATION		DATE	Ohjoon Kwon

WHEREAS, WE.

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Done at _		, on	
	LOCATION	DATE	Ying Duan
Done at _	and a sum of the state of the s	, on DATE	
	LOCATION	DATE	Chulkyu Lee
Done at _	AM	, on 1 1/29/20/8	Shih-Wei Chou
	LOCATION	DATĚ	Shih-Wei Chou
Done at _		_, on	
	LOCATION	DATE	Harry Dang
Done at _		on	
	LOCATION	DATE	Ohioon Kwon

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Done at		on	
	LOCATION	onDATE	Ying Duan
Done at	LOCATION,	on	
	LOCATION	DATE	Chulkyu Lee
Done at	LOCATION ,	on	Shih-Wei Chou
	ECCATION	DATE	Sain-wei Chou
Done at	San Diego,	on <u>/0//4//5</u> DATE	Harry Dang
Done at		on	
		DATE	Ohjoon Kwon

WHEREAS, WE,

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PATENT

QUALCOMM Ref. No. 153252 Page 3 of 3

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _		_, on	
	LOCATION	DATE	Ying Duan
Done at _		, on	
-	LOCATION	DATE	Chulkyu Lee
Done at _		, on	
	LOCATION	DATE	Shih-Wei Chou
Done at _	i o o i mio	_, on	
Done at	LOCATION San Divan	, on <u>しんほんごう</u>	Shih-Wei Chou
· 	LOCATION	DATE	Object Kwen

PATENT REEL: 036926 FRAME: 0527

RECORDED: 10/30/2015